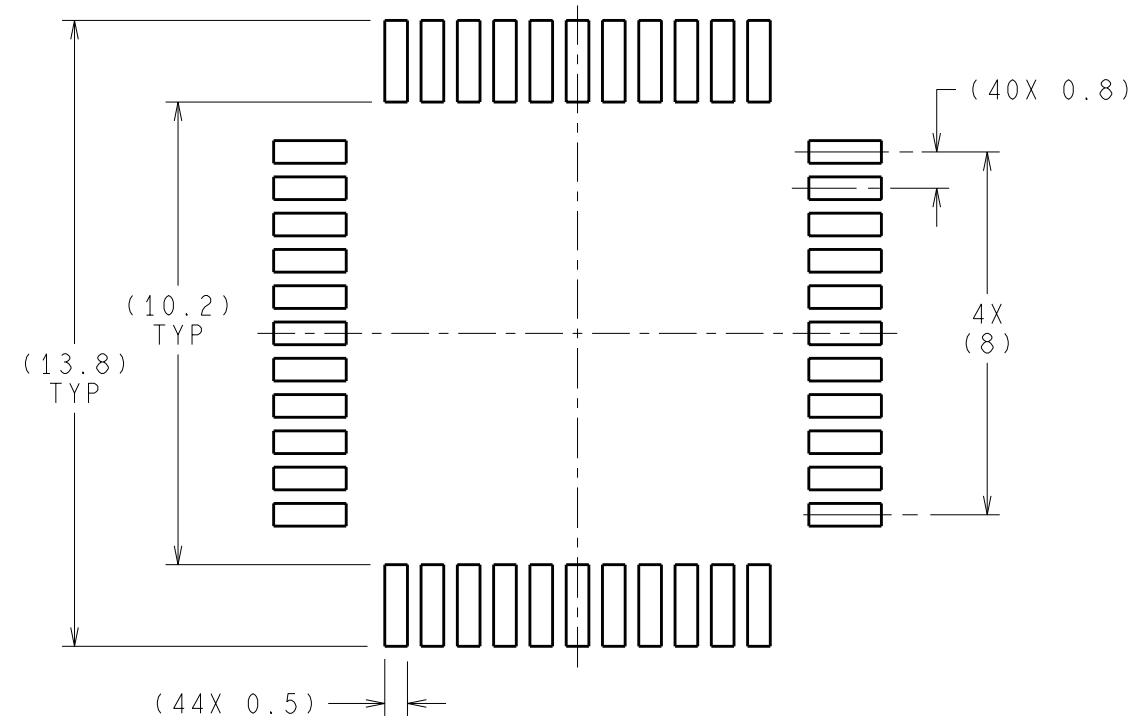
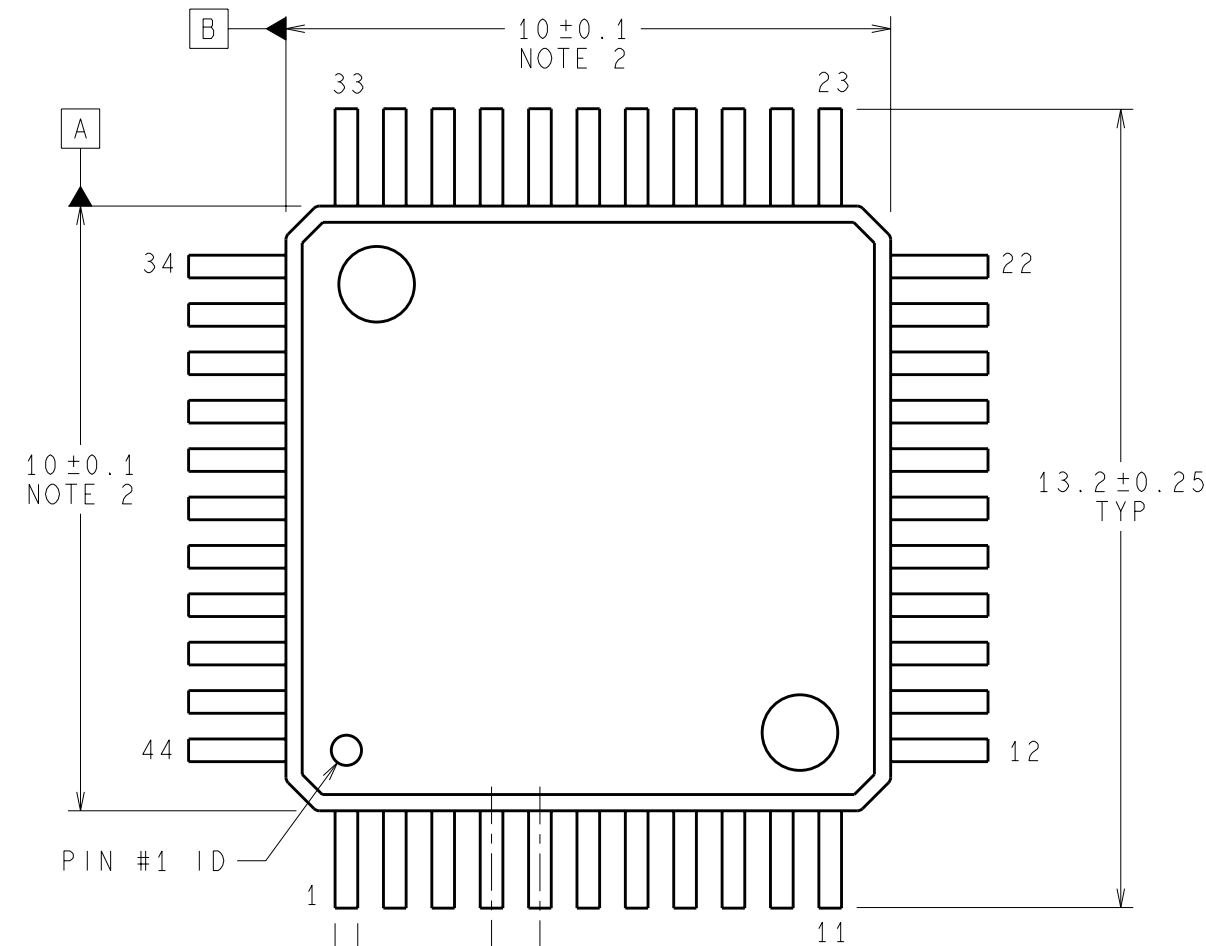


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	REVISE & REDRAW PER ECN	11035	07/24/1995	DEG/HJK
E	ADD EJECTOR PINS; UPDATE DWG PER CURRENT STDS	953	02/05/2003	TL/RW

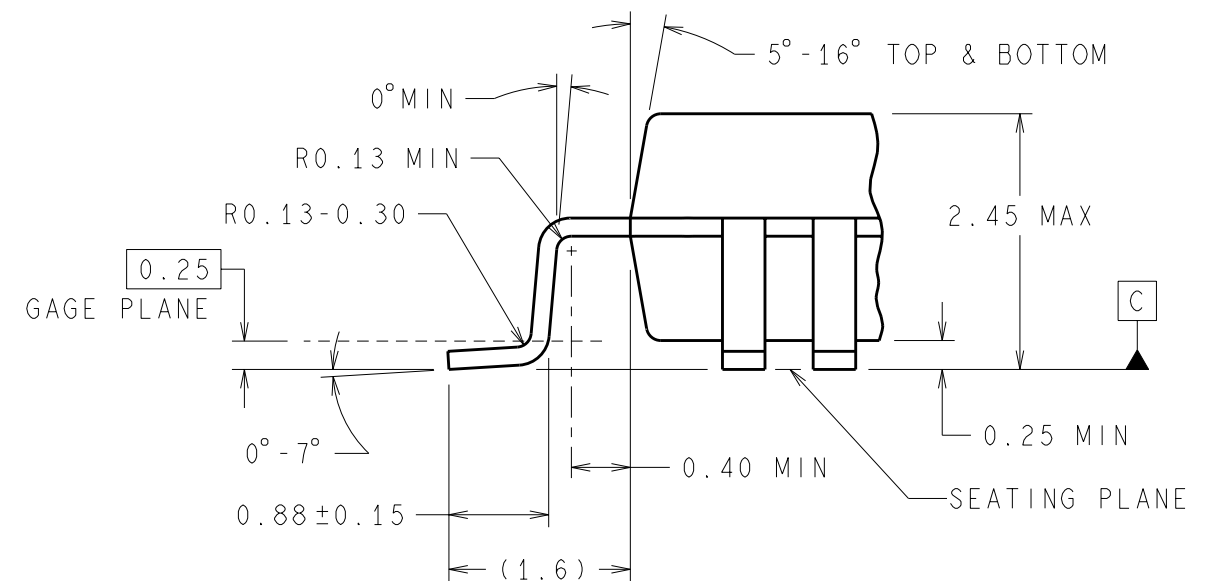
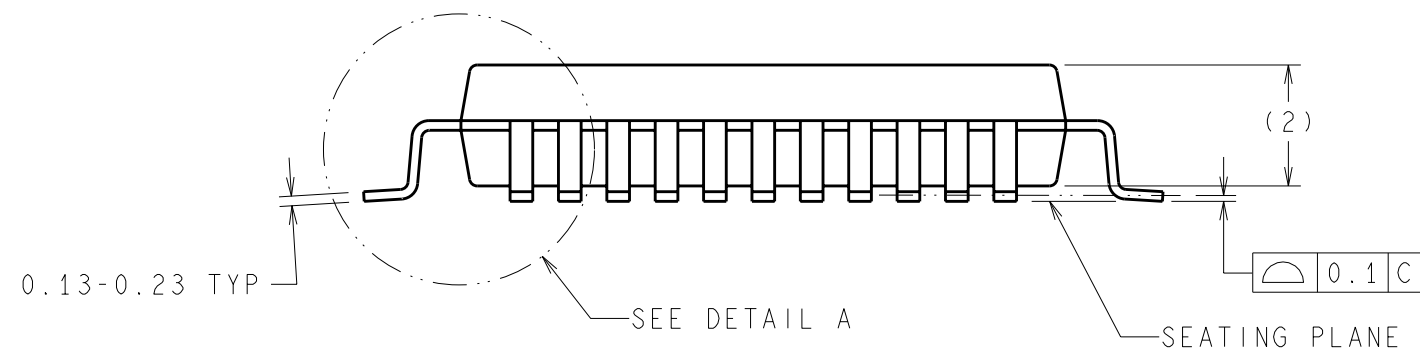


RECOMMENDED LAND PATTERN

44X 0.30-0.45  
NOTE 3

40X 0.8

⊕ 0.2 (M) C A (S) B (S)



NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.15mm.
- REFERENCE JEDEC REGISTRATION MO-108, VARIATION AA-1.

DIMENSIONS ARE IN MILLIMETERS

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	DE.Grady	07/10/95		
DFTG. CHK.	MARTA SUCHY	02/05/2003	PQFP, JEDEC METRIC, (S), 10 X 10 X 2.0mm, 44 LEAD	
ENGR. CHK.	RANDALL WALBERG	02/05/2003		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-VGZ44A	E
FORMERLY: N/A			SHEET 1 of 1	